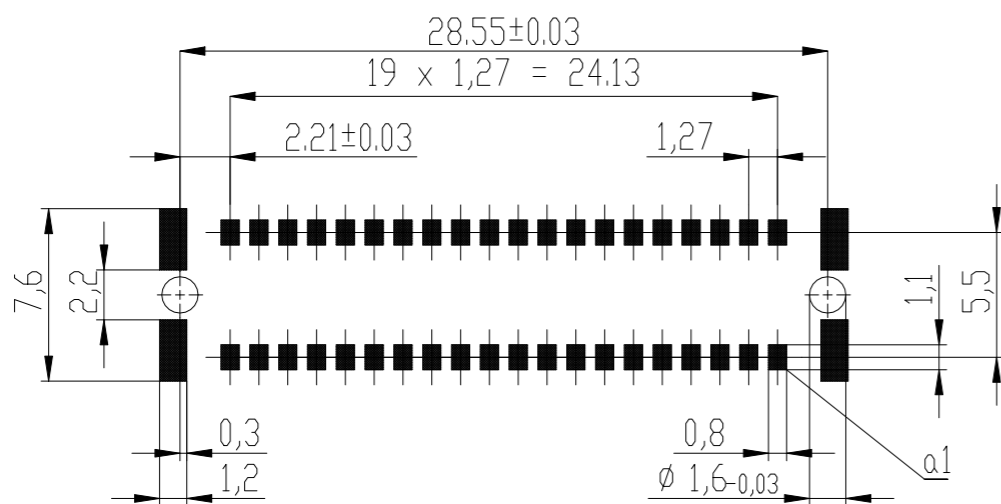
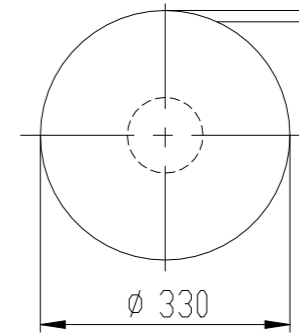


Leiterplatten-Layout Vorschlag für SMT  
PCB-Layout Proposal for SMT

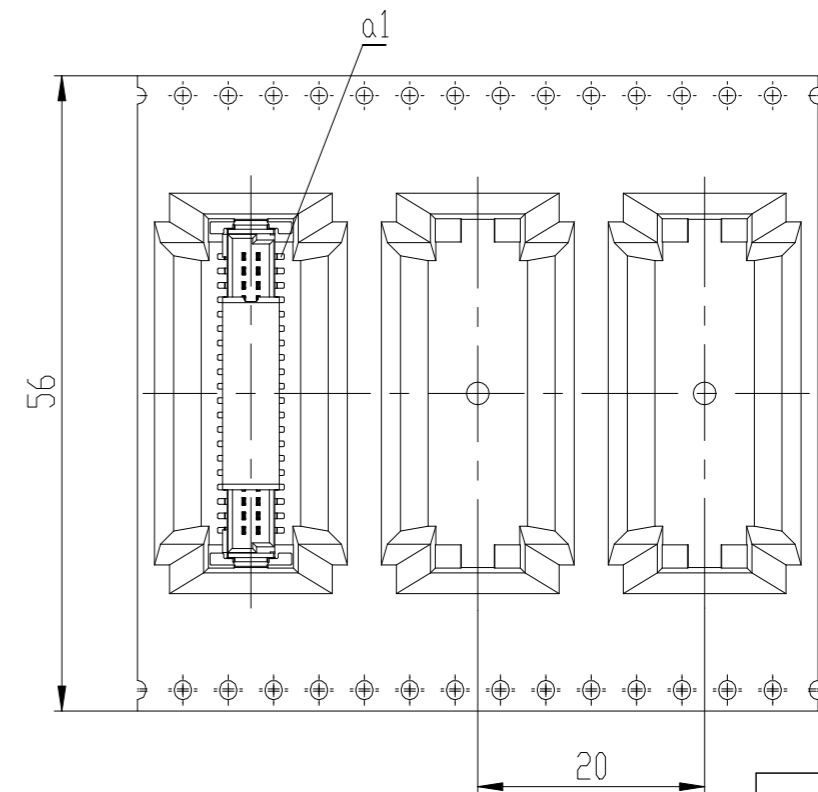
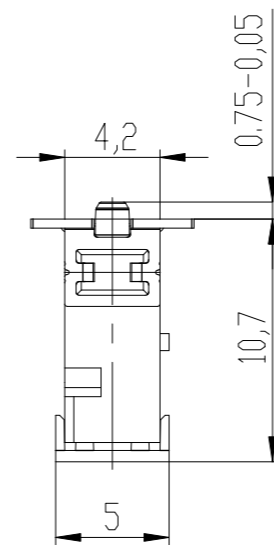


Anforderungsstufe 1  
performance level 1  
Kontaktbereich vergoldet  
mating area gold plating  
Anschlussbereich verzinkt 4-6 µm  
terminal area 4-6 µm tin plating  
Koplanarität der Anschlüsse ≤ 0,1 mm  
coplanarity area of termination ≤ 0,1 mm

Verpackt im Gurt in Anlehnung an DIN IEC 60286-3  
tape on reel packaging according to DIN IEC 60286-3  
Verpackungseinheit: 250 Stück  
packaging unit: 250 pcs



Abspulrichtung - Reel off Direction



BA 8-23 - hohe Bauhöhe  
type 8-23 - High Profile

Information:	Tolerances	Scale 3:1	Designation ERNI-Messertl. SMC-Q 40-SMD-BA8-23 Male SMC-Q 40-SMD-type8-23	
	Customer drawing: THIS DRAWING IS A CONTROLLED DOCUMENT.			
f	06.11.2018	TE Connectivity	C- 254417-E	I
Index	Date			Class SMCQ

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)